

Title (en)  
METHOD OF ANALYZING AND UTILIZING SURFACE TOPOGRAPHY FOR TARGETED LOCAL THERMAL MANAGEMENT IN ADDITIVE MANUFACTURING SYSTEMS

Title (de)  
VERFAHREN ZUR ANALYSE UND VERWENDUNG DER OBERFLÄCHENTOPOGRAFIE ZUR GEZIELTEN LOKALEN WÄRMEVERWALTUNG IN SYSTEMEN ZUR GENERATIVEN FERTIGUNG

Title (fr)  
PROCÉDÉ D'ANALYSE ET D'UTILISATION D'UNE TOPOGRAPHIE DE SURFACE POUR UNE GESTION THERMIQUE LOCALE CIBLÉE DANS DES SYSTÈMES DE FABRICATION ADDITIVE

Publication  
**EP 4392234 A1 20240703 (EN)**

Application  
**EP 22821734 A 20221102**

Priority  
• US 202117522475 A 20211109  
• US 2022048667 W 20221102

Abstract (en)  
[origin: WO2023086250A1] A method for 3D printing a part with an additive manufacturing system includes printing a first portion (302)(308) of a part (342) in a layerwise manner and analyzing a topology (344) of the first portion (302)(308) of the part. The method includes determining a tool path for printing a second portion (306) of the part on a surface of the first portion (302) of the part (346), and pre-heating the first portion (302)(308) of the part along the tool path as a function of the topological analysis of the first portion of the part (348). The method includes printing the second portion (306) of the part along the tool path (350).

IPC 8 full level  
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